

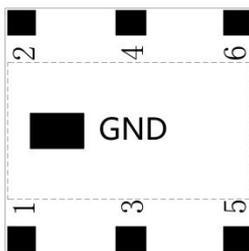
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

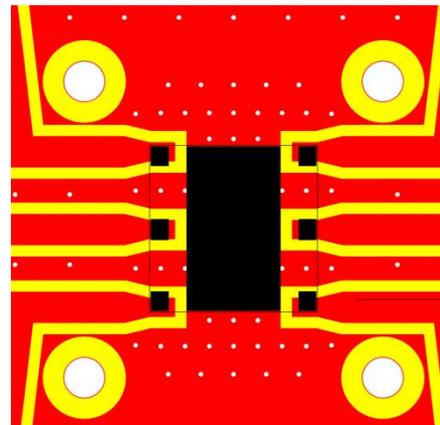
NO.	Specification				
		LPF1	LPF2	LPF3	
1	Frequency range (MHz)	225~330	330~480	480~678	
2	Insertion Loss (dB) @25°C	1.2	0.8	0.8	
3	VSWR (In BW)	1.5	1.5	1.5	
4	Ripple	1.0	1.0	1.0	
5	Impedance ( $\Omega$ )	50	50	50	
6	Attenuation (dB)	450~990MHZ	50	-	-
		660~1440 MHZ	-	50	-
		960~2034 MHZ	-	-	50
<b>Operating &amp; Storage Condition (Component)</b>					
Operation Temperature Range: -40°C ~ +85°C					
Storage Temperature Range: -40°C ~ +85°C					
<b>Storage Condition before Soldering (Included packaging material)</b>					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

### Construction



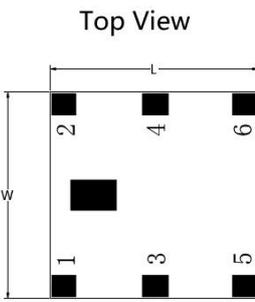
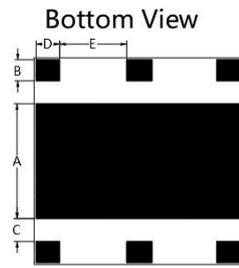
PIN	Connection	PIN	Connection
1	LPF1 input Port	2	LPF1 output Port
3	LPF2 input Port	4	LPF2 output Port
5	LPF3 input Port	6	LPF3 output Port

### Mounting Considerations

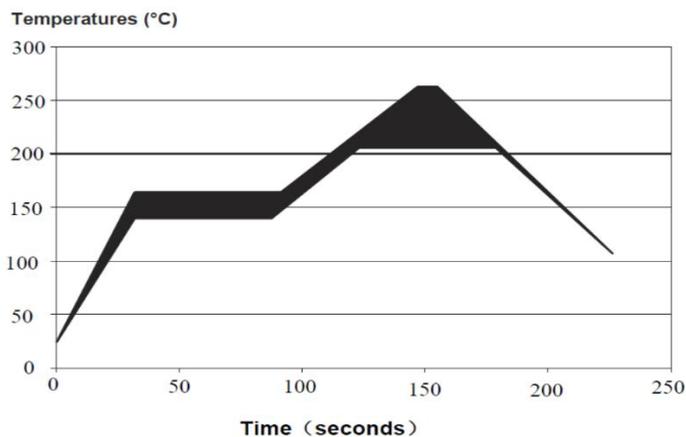


Unit: mm  
Line width to be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness

### Dimensions

Figure	Symbol	Dimension (mm)
 <p>Top View</p>	L	9.00 ± 0.10
	W	9.00 ± 0.10
	T	2.40 ± 0.10
	A	5.00 ± 0.10
	B	0.92 ± 0.10
	C	1.00 ± 0.10
	D	1.10 ± 0.10
 <p>Bottom View</p>	E	2.90 ± 0.10
 <p>Side View</p>		

### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.